

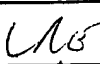


FORM PTO-1449	U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE	ATTY. DOCKET NO. MEISS89.001AUS	APPLICATION NO. 10/090,083
SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT BY APPLICANT (USE SEVERAL SHEETS IF NECESSARY)		APPLICANT FARASSAT, Farhad	
		FILING DATE March 1, 2002	GROUP 1725

U.S. PATENT DOCUMENTS							
EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE (IF APPROPRIATE)
No	1	US 3,572,108	03/1971	McShane et al.			
	2	US 4,445,378	05/1984	Zuckerwar			
	3	US 4,453,414	06/1984	Ronemus et al.			
	4	US 4,619,397	10/1986	Urban			
	5	US 4,895,028	01/1990	Mayer			
	6	US 4,907,458	03/1990	Biggs et al.			
	7	US 4,984,730	01/1991	Göbel et al.			
	8	US 5,213,249	05/1993	Long et al.			
	9	US 5,275,058	01/1994	Pham et al.			
	10	US 5,314,105	05/1994	Farassat			
	11	US 6,178,823	01/2001	Sykes			
	12	US 5,889,210	03/1999	Inoue			
	13	US 6,178,823	01/2001	Sykes			

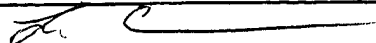
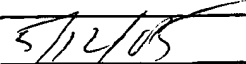
FOREIGN PATENT DOCUMENTS								
EXAMINER INITIAL		DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
							YES	NO
No ↓	14	EP 0263542	08/1987	Europe			n/a	
	15	JP 2-90038	03/1990	Japan			abstract only	
	16	GB 2271305	04/1994	Great Britain			n/a	
	17	DE 4447073	07/1996	Germany			abstract only	
	18	EP 0772036	05/1997	Europe			n/a	
	19	JP 2001-118887	04/2001	Japan			abstract only	

EXAMINER	DATE CONSIDERED
	5/12/05
*EXAMINER: INITIAL IF CITATION CONSIDERED, WHETHER OR NOT CITATION IS IN CONFORMANCE WITH MPEP 609; DRAW LINE THROUGH CITATION IF NOT IN CONFORMANCE AND NOT CONSIDERED, INCLUDE COPY OF THIS FORM WITH NEXT COMMUNICATION TO APPLICANT.	

FORM PTO-1449 U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT BY APPLICANT (USE SEVERAL SHEETS IF NECESSARY)	ATTY. DOCKET NO. MEISS69.001AUS	APPLICATION NO. 10/090,083
	APPLICANT FARASSAT, Farhad	
	FILING DATE March 1, 2002	GROUP 1725

EXAMINER INITIAL	OTHER DOCUMENTS (INCLUDING AUTHOR, TITLE, DATE, PERTINENT PAGES, ETC.)
	20 "Bond testing enters mainstream PCB assembly" by Paul WALTER, Microelectronics Journal, Mackinstosh Publications LTD. Luton, GB, Bd. 27, Nr. 1, (February 1996)
	21 "An Improved Wire Bond Pull Test" by Shankara PRASAD and Ali SABOUI, Solid State Technology, Cowan Publ. Corp., Washington, US, Bd. 34, Nr. 6, (June 1991)
	22 "Wire Bond Pull Testing Understanding the Geometric Resolution of Forces" by Gil PERLBERG and Cyndy ENMAN, Advanced Packaging, IHS Publishing Group, US, Bd. 3, Nr. 1, (1994)

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EXAMINER 	DATE CONSIDERED 
*EXAMINER: INITIAL IF CITATION CONSIDERED, WHETHER OR NOT CITATION IS IN CONFORMANCE WITH MPEP 608; DRAW LINE THROUGH CITATION IF NOT IN CONFORMANCE AND NOT CONSIDERED, INCLUDE COPY OF THIS FORM WITH NEXT COMMUNICATION TO APPLICANT.	